SDAS187A – APRIL 1982 – REVISED DECEMBER 1994

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

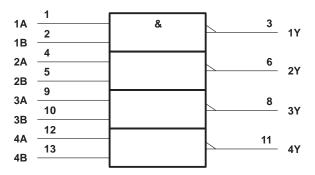
description

These devices contain four independent 2-input positive-NAND gates. They perform the Boolean functions $Y = \overline{A \cdot B}$ or $Y = \overline{A + B}$ in positive logic.

The SN54ALS00A and SN54AS00 are characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ALS00A and SN74AS00 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)											
INP	UTS	OUTPUT									
Α	В	Y									
Н	Н	L									
L	Х	Н									
Х	L	Н									

logic symbol[†]



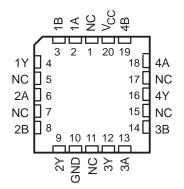
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

SN54ALS00A, SN54AS00 ... J PACKAGE SN74ALS00A, SN74AS00 ... D OR N PACKAGE (TOP VIEW)

	(,	
1A 1B 1Y 2A 2B 2Y GND	2 3 4 5	14 13 12 11 10 9 8	V _{CC} 4B 4A 4Y 3B 3A 3Y

SN54ALS00A, SN54AS00 . . . FK PACKAGE (TOP VIEW)



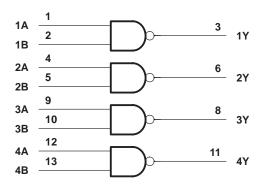
NC - No internal connection

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input voltage, V _I		
Operating free-air temperature range, TA:	: SN54ALS00A	–55°C to 125°C
	SN74ALS00A	0°C to 70°C
Storage temperature range		-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	54ALS0	0A	SN	74ALS0)A	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
	Level benef Second on Research			0.8‡			0.8	
VIL	Low-level input voltage			0.7§				V
ЮН	High-level output current			-0.4			-0.4	mA
IOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

[‡] Applies over temperature range – 55°C to 70°C

§ Applies over temperature range 70°C to 125°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS					74ALS0	DA	
PARAMETER	TEST C	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	Ij = -18 mA			-1.2			-1.5	V
VOH	V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V _{CC} –	2		V _{CC} -2	2		V
N/		$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	N/
V _{OL}	$V_{CC} = 4.5 V$	$I_{OL} = 8 \text{ mA}$					0.35	0.5	V
lj	V _{CC} = 5.5 V,	VI = 7 V			0.1			0.1	mA
IIН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
١ _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
IO‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
ICCH	V _{CC} = 5.5 V,	$V_{I} = 0$		0.5	0.85		0.5	0.85	mA
ICCL	V _{CC} = 5.5 V,	V _I = 4.5 V		1.5	3		1.5	3	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	ТО (ОИТРИТ)	CL RL T _A	$C = 4.5 V$ to 5.5 $= 50 pF$, $= 500 \Omega$, $= MIN \text{ to MAX}^{\$}$ SOOA SN74A MAX MIN 15 3 9 2	; 2, o MAX§		UNIT
			SN54AI MIN			LS00A MAX	
^t PLH	A or B	v	3	15	3	11	ns
^t PHL		-	2	9	2	8	115

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} Input voltage, V _I	
Operating free-air temperature range, T _A : SN54AS00	–55°C to 125°C
SN74AS00	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		S	N54AS0	0	S	SN74AS00		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-2			-2	mA
IOL	Low-level output current			20			20	mA
T _A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS					V74AS0)	
PARAMETER	TEST C	ONDITIONS	MIN T	YP‡ N	/IAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	I _I = -18 mA			-1.2			-1.2	V
VOH	$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			V _{CC} -2			V
VOL	V _{CC} = 4.5 V,	I _{OL} = 20 mA		0.35	0.5		0.35	0.5	V
lj	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
ΙIΗ	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
١	$V_{CC} = 5.5 V,$	$V_{ } = 0.4 V$			-0.5			-0.5	mA
۱ _O §	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-30	-	-112	-30		-112	mA
Іссн	V _{CC} = 5.5 V,	$V_{I} = 0$		2	3.2		2	3.2	mA
ICCL	V _{CC} = 5.5 V,	V _I = 4.5 V		10.8	17.4		10.8	17.4	mA

[‡] All typical values are at V_{CC} = 5 V, T_A = 25° C.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

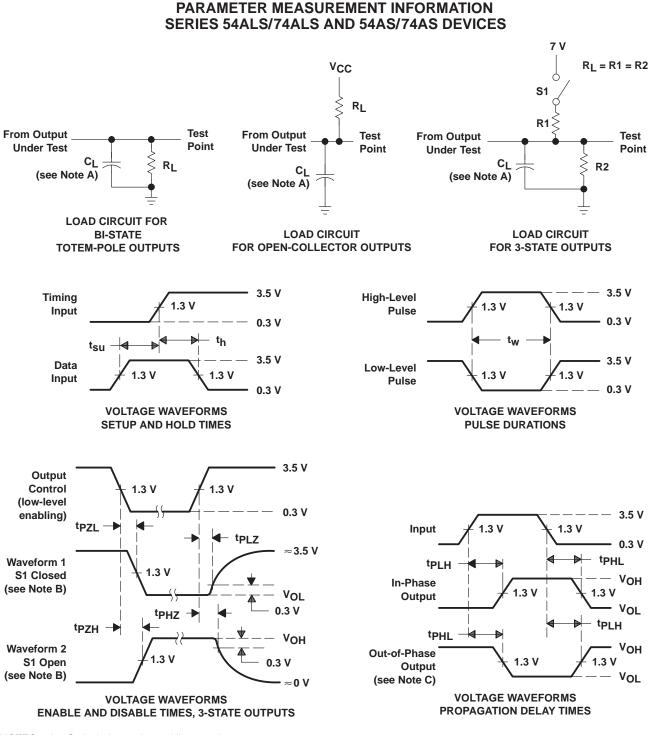
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL RL	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX¶					
			SN54	AS00	SN74/	AS00			
			MIN	MAX	MIN	MAX			
^t PLH	A or B	v	1	5	1	4.5	ns		
^t PHL	A UI B		1	5	1	4	115		

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_f = t_f = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.
- . The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





31-May-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
5962-86833012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86833012A SNJ54ALS 00AFK	Samples
5962-8683301DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8683301DA SNJ54ALS00AW	Samples
JM38510/37001B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37001B2A	Samples
JM38510/37001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37001BCA	Samples
M38510/37001B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37001B2A	Samples
M38510/37001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37001BCA	Samples
SN54ALS00AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS00AJ	Samples
SN54AS00J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS00J	Samples
SN74ALS00AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS00A	Samples
SN74ALS00ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G00A	Samples
SN74ALS00ADBRE4	ACTIVE	SSOP	DB	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74ALS00ADBRG4	ACTIVE	SSOP	DB	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74ALS00ADE4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74ALS00ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS00A	Samples
SN74ALS00ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS00A	Samples
SN74ALS00ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS00A	Samples
SN74ALS00ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS00A	Samples



PACKAGE OPTION ADDENDUM

31-May-2014

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samp
SN74ALS00AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS00AN	Samp
SN74ALS00AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74ALS00ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS00AN	Samp
SN74ALS00ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS00A	Samp
SN74ALS00ANSRE4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Samp
SN74ALS00ANSRG4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Samj
SN74AS00D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS00	Samj
SN74AS00DE4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Sam
SN74AS00DG4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Sam
SN74AS00DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS00	Sam
SN74AS00DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS00	Sam
SN74AS00DRG4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Sam
SN74AS00N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS00N	Sam
SN74AS00NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS00N	Sam
SN74AS00NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS00	Sam
SN74AS00NSRE4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Sam
SN74AS00NSRG4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Sam
SNJ54ALS00AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86833012A SNJ54ALS 00AFK	Sam
SNJ54ALS00AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54ALS00AJ	Sam



31-May-2014

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54ALS00AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8683301DA SNJ54ALS00AW	Samples
SNJ54AS00FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54AS 00FK	Samples
SNJ54AS00J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS00J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

31-May-2014

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ALS00A, SN54AS00, SN74ALS00A, SN74AS00 :

- Catalog: SN74ALS00A, SN74AS00
- Military: SN54ALS00A, SN54AS00
- NOTE: Qualified Version Definitions:
 - Catalog TI's standard catalog product
 - Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS00ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74ALS00ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS00ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS00DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS00NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

26-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS00ADBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74ALS00ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74ALS00ANSR	SO	NS	14	2000	367.0	367.0	38.0
SN74AS00DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74AS00NSR	SO	NS	14	2000	367.0	367.0	38.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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